



SPECIFICATION

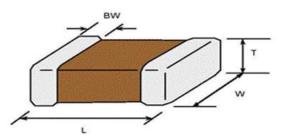
(Reference sheet)

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : • Description :
- CL03C030CA3GNNH CAP, 3pF, 25V, ±0.25pF, C0G, 0201

- A. Samsung Part Number

			<u>CL</u> ①	<mark>03</mark> ②	<u>C</u> 3	<u>030</u> ④	<u>C</u> 5	<mark>_</mark> 6	<u>3</u> 7	<u>G</u> 8	<u>N</u> 9	<u>N</u> 10	<u>Н</u> 11			
1	Series	Samsung M	lulti-lay	er Ce	eram	ic Cap	acito	or								
2	Size	0201 (in	nch coc	le)		L: (0.60	± 0.03	}	mm		W:	0.30 ±	0.03	mm	
3	Dielectric	C0G					8	Inner	elect	trode			Cu			
4	Capacitance	3 pF						Termi	inatio	on			Cu			
5	Capacitance	±0.25 pF						Platin	g				Sn 100%	, D	(Pb Free	e)
	tolerance						9	Produ	ıct				Normal			
6	Rated Voltage	25 V					10	Speci	al				Reserve	d for f	uture us	e
\bigcirc	Thickness	0.30 ±0	0.03 i	mm			1	Packa	aging	J			Cardboa	rd Typ	oe, 7" re	el

B. Structure and dimension



Samsung P/N	Dimension(mm)								
(Lead Free)	L	W	Т	BW					
CL03C030CA3GNNH	0.60±0.03	0.30±0.03	0.30±0.03	0.15±0.05					

C. Samsung Reliability Test and Judgement condition

	Performance	Test condition				
Capacitance	Within specified tolerance	1M±±10% 0.5~5Vrms				
Q	460 min					
Insulation	10,000Mohm or 500Mohm . <i>μ</i> F	Rated Voltage 60~120 sec.				
Resistance	Whichever is smaller					
Appearance	No abnormal exterior appearance	Microscope (×10)				
Withstanding	No dielectric breakdown or	300% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	COG					
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)					
Adhesive Strength	No peeling shall be occur on the	200g F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change :	Bending to the limit (1mm)				
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5℃, 3±0.3sec.				
		(preheating : 80~120℃ for 10~30sec.)				
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.				
Soldering heat	within ±2.5% or ±0.25pF whichever is larger					
_	Tan δ, IR : initial spec.					
Vibration Test	Capacitance change :	Amplitude : 1.5mm				
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	From 10Hz to 55Hz (return : 1min.)				
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)				
Moisture	Capacitance change :	With rated voltage				
Resistance	within $\pm 7.5\%$ or ± 0.75 pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs				
	Q : 110 min					
	IR : 500Mohm or 25Mohm · μF					
	Whichever is smaller					
High Temperature	Capacitance change :	With 200% of the rated voltage				
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature				
	Q : 230 min	1000+48/-0hrs				
	IR : 1,000Mohm or 50Mohm · μF					
	Whichever is smaller					
Temperature	Capacitance change :	1 cycle condition				
Cycling	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	Min. operating temperature \rightarrow 25 °C				
	Tan δ, IR : initial spec.	\rightarrow Max. operating temperature \rightarrow 25 °C				
		5 cycle test				

* The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.